



## **CyberOptics Presents Best Known Measurement Methods in Semiconductor Manufacturing Environments at CS ManTech**

*Company discusses most effective ways to improve yield and tool uptimes using high-precision measurement devices*

**Minneapolis, Minnesota** — May 12, 2016— [CyberOptics® Corporation](#) (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, will present at the [CS ManTech Conference](#), the industry's most important event centered around compound semiconductor processing, testing, design and applications at the Hyatt Regency in Miami, Florida on May 17 at 6:05 p.m. The company will also have an exhibit featuring the WaferSense® wireless measurement portfolio in booth # 510 during the conference May 16 – 19.

CS ManTech's mission is to foster communication between industry, academia, and government. Three of their key goals include facilitating technical cooperation within the compound semiconductor industry through discussions on semiconductor manufacturing technology problems, helping advance manufacturing capabilities and to establish and maintain credible, high professional standards for the industry. At the conference, Allyn Jackson, Field Applications Engineer and Director of Sales for U.S and Europe at CyberOptics, will present "Best Practices for Measurements in Semiconductor Environments."

"Legacy measurement methods are not real-time, can be complicated or inefficient, and can be costly when tools need to be taken offline for various processes," said Allyn Jackson, "The use of high-precision, wireless measurement devices can significantly increase yields and tool uptime in semiconductor environments."

Solutions reviewed in the case study will include CyberOptics' Airborne Particle Sensors (APS2) which are widely adopted by semiconductor fabs and equipment OEMs worldwide to wirelessly monitor airborne particles, and its recently launched and rapidly adopted, Auto Multi Sensors (AMS) which easily capture relative humidity (RH), vibration and leveling measurements – all in real-time.

### **About the WaferSense and ReticleSense Line**

WaferSense® and ReticleSense® Airborne Particle Sensors enable equipment engineers to shorten equipment qualification, release to production and maintenance cycles, all while reducing expenses. Customers have experienced up to 88% time savings, up to 95% reduction in costs, and up to 20X the through-put with half the manpower resource requirements using the WaferSense sensors relative to legacy surface scan wafer methods.

The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS), the Airborne Particle

Sensor (APS), the next-generation Airborne Particle Sensor (APS2) and the new Auto Multi Sensor (AMS) are available in various wafer shaped form factors depending on the device, including 150mm, 200mm, 300mm and 450mm wafer sizes. The ReticleSense measurement portfolio including the Airborne Particle Sensor (APSR & APSRQ) and next-generation APS2, the Auto Leveling System (ALSR) and the new Auto Multi Sensor (AMSR) are available in a reticle shaped form factor.

For more information about the entire line of CyberOptics solutions please visit the company's website at [www.cyberoptics.com](http://www.cyberoptics.com).

### **About CyberOptics**

CyberOptics Corporation (NASDAQ: CYBE) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics sensors are being used in general purpose metrology and 3D scanning, surface mount technology (SMT) and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of its key vertical segments. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; expectations regarding our 2014 acquisition of Laser Design, Inc. (LDI) and its impact on our operations; and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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For additional information, contact:

Lisa Grau, GrauPR, 760-207-9090, [lisa@graupr.com](mailto:lisa@graupr.com)

Carla Furanna, CyberOptics, 952-820-5837, [cfuranna@cyberoptics.com](mailto:cfuranna@cyberoptics.com)